<table>
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<tr>
<th>Document Title</th>
<th>Limitations and Deviations for CAL FM Test-Stand #14</th>
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## CHANGE HISTORY LOG

<table>
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<tr>
<th>Revision</th>
<th>Effective Date</th>
<th>Description of Changes</th>
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<tr>
<td>01</td>
<td>01 December 2004</td>
<td>Original</td>
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1. **SCOPE**

This document lists

- the environmental limitations and
- the differences of the test-stand shipped compared to the released test-stand drawings

2. **ENVIRONMENTAL CONDITION**

- The test-stand was only tested at room-temperature.

3. **DIFFERENCES TO RELEASE DRAWINGS**

3.1 **Tower Electronics Module**

- LAT-DS-01650-02 - Schematic Diagram, TEM CCA
- LAT-TD-02230-01 - Bill of Materials, TEM CCA
  - For resistors R648, R649, R650, R651 instead of single 50 Ohm value, two 100 Ohm resistors in parallel are used. They loaded with one soldered on top of second resistor.
- LAT-DS-01646-04 - Circuit Card Assembly, TEM DAQ
- LAT-DS-01649-05 - Printed Wire Board, TEM
- LAT-DS-02583-01 - PWB Fab, Loading and Assembly
- LAT-DS-02588-02 - Connector and Cable Assembly, TEM CCA
- LAT-DS-00554-06 - TEM Box Base
  - Part is fully electroless nickel plated, no hard anodize was used
- LAT-DS-00555-06 - TEM Box Lid
  - Part is fully electroless nickel plated, no hard anodize was used
- LAT-DS-01481-04 - Assembly, Tower Electronics Module
  - Assy number not marked on chassis

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- LAT-DS-01026-02 - TEM Connector Plate – countersink both sides equal
- LAT-DS-01031-02 - TEM Connector Pin
- LAT-TD-01880-01 - VHDL, LAT TEM GTIC FPGA
- LAT-TD-01881-01 - VHDL, LAT TEM GTIU FPGA
- LAT-DS-03582-01 - Spacer, TEM Connector – dimension 0.72 in overall length

FPGA version numbers:
  - U45 – GTIC – version 1
  - U62 – COMMCNTL version 1 (Preprogrammed firmware version 9)

4. **CHANGES FROM TEST-PROCEDURE**

The test-procedure was in the process of official LAT-DOC release while the tests were performed. No changes to the procedure were done between the executing the tests and official release of the procedure.

The TEM unit was not tested over different frequencies or temperatures, and those steps are marked as skipped in the test result documentation.